



EFW/B

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR Edmund D. Blackshear) EXAMINER: A. O. Williams
SERIAL NO: 10/719,334) ART UNIT: 2826
FILING DATE: November 21, 2003) DATE: December 28, 2005
TITLE: OVERLAP STACKING OF CENTER BUS BONDED MEMORY
CHIPS FOR DOUBLE DENSITY AND METHOD OF
MANUFACTURING THE SAME

TRANSMITTAL OF FORMAL DRAWINGS


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
ATTN: OFFICIAL DRAFTSPERSON

Dear Sir:

Enclosed are formal drawings for the above-identified application. Kindly replace the informal drawings, as filed, with the enclosed 4 sheets of drawings marked "REPLACEMENT SHEETS." No new matter has been added.

Please charge the Assignee IBM Corporation Deposit Account No. **09-0458** for any fee related to the acceptance of the attached Formal Drawings. A duplicate copy of this letter is enclosed for that purpose.

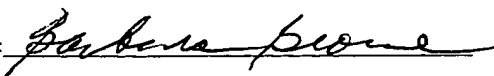
Respectfully submitted,


Robert Curcio
Reg. No. 44,638

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CERTIFICATE OF MAILING UNDER 37 CFR 1.8

I hereby certify that I am depositing the enclosed or attached correspondence with the United States Postal Service as first class mail in an envelope addressed to the, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, ATTENTION OFFICIAL DRAFTSPERSON.

Name of person mailing paper Barbara Browne Date: December 28, 2005 Signature: 
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